

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.	:	10/598,471	Confirmation No. 5838
Applicant	:	Yuichiro Shindo et al.	
371 Filed	:	August 31, 2006	
Art Unit	:	1793	
Examiner	:	Vanessa T. Velasquez	
Customer No.	:	00270	
Title	:	HIGH-PURITY RU POWDER, SPUTTERING TARGET OBTAINED BY SINTERING THE SAME, THIN FILM OBTAINED BY SPUTTERING THE TARGET AND PROCESS FOR PRODUCING HIGH-PURITY RU POWDER	

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO RESTRICTION REQUIREMENT

Sir:

This is a timely response to the written Restriction Requirement dated September 8, 2008.

Election

In the present application, Applicants elect without traverse to prosecute the invention directed to a ruthenium powder, sputtering target and thin film. Thus, Group I is elected and includes claims 1 and 8-22.

Please charge any deficiency or credit any overpayment for entering this Response to our deposit account no. 08-3040.

Respectfully submitted,
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